

**IN THE CLAIMS:**

Claims 31 through 94 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

**Listing of Claims:**

1. (Previously presented) An apparatus for selectively applying different amounts of pressure to a plurality of locations on a backside of a substantially circular semiconductor device structure, comprising:  
a support structure configured to receive the semiconductor device structure;  
a plurality of pressurization rings within the support structure, each of the plurality of pressurization rings being configured to apply pressure to a correspondingly annular region of the backside of the semiconductor device structure assembled with the support structure; and  
a plurality of magnetic controllers, each of the plurality of magnetic controllers associated with a corresponding one of the plurality of pressurization rings.
2. (Previously presented) The apparatus of claim 1, wherein each of the plurality of pressurization rings comprises a magnetized material.
3. (Previously presented) The apparatus of claim 2, wherein each of the plurality of magnetic controllers is positioned adjacent the corresponding one of the plurality of pressurization rings and is oriented to repel the corresponding one of the plurality of pressurization rings.

4. (Previously presented) The apparatus of claim 2, wherein each of the plurality of magnetic controllers is positioned opposite the semiconductor device structure assembled with the support structure from the corresponding one of the plurality of pressurization rings and is oriented to attract the corresponding one of the plurality of pressurization rings.

5. (Previously presented) The apparatus of claim 1, wherein each of the plurality of pressurization rings comprises a material that is attracted to a magnetic field.

6. (Previously presented) The apparatus of claim 5, wherein each of the plurality of magnetic controllers is located so as to magnetically attract the corresponding one of the plurality of pressurization rings.

7. (Previously presented) The apparatus of claim 6, wherein, as at least one pressurization ring of the plurality of pressurization rings is attracted toward a corresponding one of the plurality of magnetic controllers, the at least one pressurization ring is configured to be biased against and to apply pressure to the backside of the semiconductor device structure at a corresponding annular region thereof.

8. (Previously presented) The apparatus of claim 5, wherein the material comprises a ferrous material.

9. (Previously presented) The apparatus of claim 5, wherein the material comprises a magnetized material.

10. (Previously presented) The apparatus of claim 1, wherein each of the plurality of magnetic controllers comprises an electromagnet.

11. (Previously presented) The apparatus of claim 1, wherein each of the plurality of magnetic controllers is configured to be moved toward and away from the corresponding one of the plurality of pressurization rings.

12. (Previously presented) The apparatus of claim 1, wherein each of the plurality of magnetic controllers is configured to bias the corresponding one of the plurality of pressurization rings against corresponding annular regions of the backside of the semiconductor device structure with a variable magnitude of force.

13. (Previously presented) An apparatus for selectively applying different amounts of pressure to a plurality of locations on a backside of a semiconductor device structure, comprising:

a support structure configured to receive the semiconductor device structure;

a plurality of independently movable pressurization structures located within the support

structure, each of the pressurization structures located and oriented adjacent a region on a backside of a semiconductor device structure upon assembly of the semiconductor device structure with the support structure; and

a plurality of actuators, each of the plurality of actuators associated with a corresponding pressurization structure of the plurality of pressurization structures so as to independently bias the corresponding pressurization structure against the backside of the semiconductor device structure assembled with the support structure.

14. (Previously presented) The apparatus of claim 13, wherein each of the plurality of pressurization structures comprises a ring.

15. (Previously presented) The apparatus of claim 13, wherein each of the plurality of actuators comprises a magnetic controller.

16. (Previously presented) The apparatus of claim 15, wherein each of the plurality of pressurization structures comprises a magnetized material.

17. (Previously presented) The apparatus of claim 15, wherein each of the plurality of pressurization structures comprises a material that is attracted to a magnetic field.

18. (Previously presented) The apparatus of claim 15, wherein each of the plurality of actuators is oriented so as to repel a corresponding pressurization structure.

19. (Previously presented) The apparatus of claim 15, wherein each of the plurality of actuators is oriented so as to attract a corresponding pressurization structure.

20. (Previously presented) The apparatus of claim 15, wherein each of the plurality of actuators comprises an electromagnet.

21. (Previously presented) The apparatus of claim 15, wherein each of the plurality of actuators is movable toward and away from a corresponding pressurization structure.

22. (Previously presented) The apparatus of claim 15, wherein each of the plurality of actuators comprises a vacuum source.

23. (Previously presented) The apparatus of claim 22, further comprising a spring associated with each of the plurality of independently movable pressurization structures, each the spring biasing a corresponding pressurization structure against the backside of the semiconductor device structure, each of the plurality of actuators being configured to pull a corresponding one of the plurality of independently movable pressurization structures away from the backside of the semiconductor device structure.

24. (Previously presented) The apparatus of claim 15, wherein each of the plurality of actuators comprises a positive pressure source.

25. (Previously presented) The apparatus of claim 24, further comprising a spring associated with each of the plurality of independently movable pressurization structures.

26. (Previously presented) The apparatus of claim 24, wherein the positive pressure source is configured to bias a corresponding pressurization structure against the backside of the semiconductor device structure assembled with the support structure.

27. (Previously presented) The apparatus of claim 15, wherein each of the plurality of actuators is configured to bias the corresponding pressurization structure against the backside of the semiconductor device structure assembled with the support structure with variable amounts of force.

28. (Previously presented) The apparatus of claim 18, wherein each of the plurality of actuators is located to force the corresponding pressurization structure against the backside of the semiconductor device structure assembled with the support structure.

29. (Previously presented) The apparatus of claim 19, wherein each of the plurality of actuators is located to pull the corresponding pressurization structure against the backside of the semiconductor device structure assembled with the support structure.

30. (Previously presented) The apparatus of claim 15, wherein each of the of pressurization structures has associated therewith a spring.

31.-94. (Cancelled)